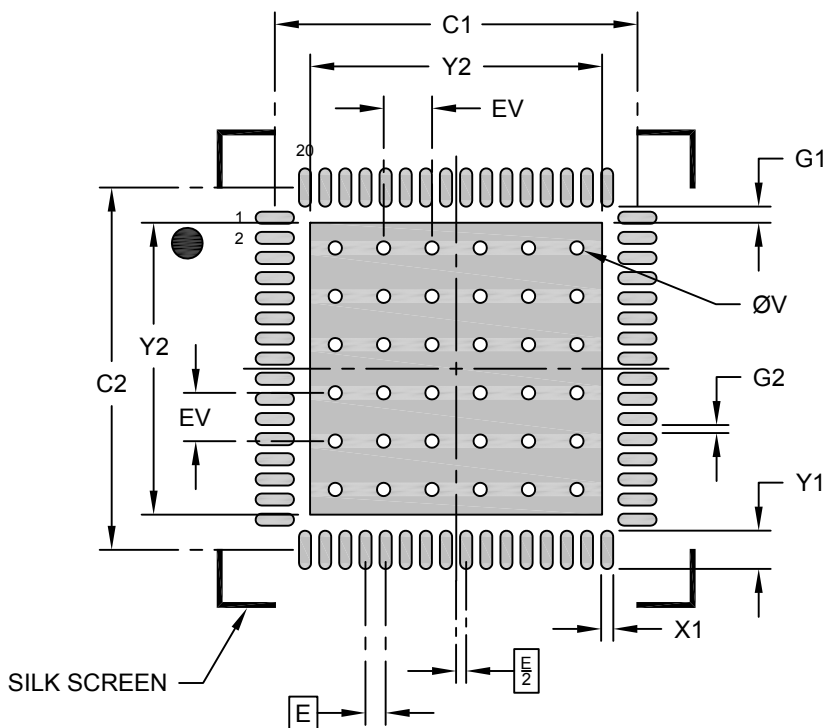


64-Lead Very Thin Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [VQFN] With 7.15 x 7.15 Exposed Pad [Also called QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	X2			7.25
Optional Center Pad Length	Y2			7.25
Contact Pad Spacing	C1		9.00	
Contact Pad Spacing	C2		9.00	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.95
Contact Pad to Center Pad (X64)	G1	0.40		
Spacing Between Contact Pads (X60)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process